Product Change Notification: MFOL-30OMBY736

Date:

29-Nov-2025

Product Category:

Ethernet Phys

Notification Subject:

CCB 7393 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material and 3280NP as a new die attach material for selected KSZ8091, KSZ8051 and KSZ8081 device families available in 32L VQFN (5x5x0.9mm) package at MTAI assembly site.

Affected CPNs:

MFOL-30OMBY736_Affected_CPN_11292025.pdf
MFOL-30OMBY736_Affected_CPN_11292025.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material and 3280NP as a new die attach material for selected KSZ8091, KSZ8051 and KSZ8081 device families available in 32L VQFN (5x5x0.9mm) package at MTAI assembly site.

Pre and Post Summary Changes:

	Pre Change	**Post Change**	**Change** (Yes/No)
Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)	No
Wire Material	Au	CuPdAu	Yes

Die Attach Material	3280	3280NP*	Yes
Molding Compound Material	G700LTD	G700LTD	No
Lead-Frame Material	A194	A194	No

Note1: *The qualification of the new PFAS-free die attach material, QMI519, was officially released via PCN #**CENO-16EGCZ399**.

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material and 3280NP as a new die attach material.

Change Implementation Status: In Progress

Estimated First Ship Date: 24 November 2025 (date code: 2548)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	February 2025					>	**October 2025**					**November 2025**				
Work Week	05	06	07	08	09		40	41	42	43	44	45	46	47	48	49
Initial PCN Issue Date		x														
Qual Report Availability										x						
Final PCN Issue Date										x						
Estimated Implementation Date															x	

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: February 04, 2025: Issued initial notification.
October 23, 2025: Issued final notification. Updated notification subject to remove KSZ8091 device family. Updated affected parts list to remove KSZ8081MNXCA, KSZ8081MNXIA, KSZ8091MNXCA, KSZ8091RNBCA, SPNZ801174, KSZ8081RNBCA-TR, KSZ8091RNBCA-TR, KSZ8081MNXCA-TR, KSZ8091MNXCA-TR, KSZ8091MNXIA-TR and KSZ8091RNBIA-TR catalog part numbers. Added a new column titled 'Change (Yes/No)' to the Pre and Post Change Summary table. Attached the qualification report. Provided estimated first ship date to be on November 24, 2025.
October 27, 2025: Re-issued final notification to add note, "Note1: *The qualification of the new PFAS-free die attach material, QMI519, was officially released via PCN #CENO-16EGCZ399." for die attach material change.
November 29, 2025: Re-issued final notification to include KSZ8081MNXCA, KSZ8081MNXIA, KSZ8091MNXCA, KSZ8091RNBCA, SPNZ801174, KSZ8081RNBCA-TR, KSZ8091RNBCA-TR, KSZ8081MNXCA-TR, KSZ8091MNXCA-TR, KSZ8091MNXIA-TR and KSZ8091RNBIA-TR catalog part numbers due to updated scope. Updated notification subject and description of change to add KSZ8091 device family.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_MFOL-30OMBY736 Qual_Report.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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